TOSHIBA

TC54256AP/AF

SILICON STACKED GATE CMOS

32,768 WORD x 8 BIT ONE TIME PROGRAMMABLE READ ONLY MEMORY

Description

The TC54256AP/AF is a 32,768 word x 8 bit one time programmable read only memory molded in a 28-pin plastic package. The TC54256AP/AF's access time is 200ns and it has a low power standby mode which reduces the power dissipation without increasing access time. The electrical characteristics and programming method are the same as for the TC57256AD UV EPROM. Once programmed, the TC54256AP/AF cannot be erased because of the use of a plastic DIP without a transparent window.

Features

Peripheral circuit : CMOSMemory cell : NMOS

· Low power dissipation

- Active : 30mA/6.7MHz - Standby : 100μA • Fast access time : 200ns

Single 5V power supply

• Fully static operation

• High speed programming mode

• Inputs and outputs TTL compatible

 Pin compatible with ROM TC53257P, TMM23256P, EPROM TMM27256D/AD, TC57256D/AD, One time PROM TMM24256P/AP, and TC54256P

Package

- TC54256AP : DIP28-P-600 - TC54256AF : SOP28-P-450

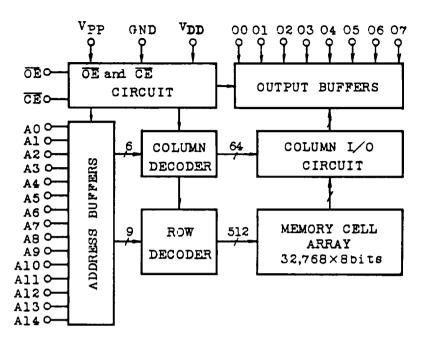
Pin Names

A0 ~ A14	Address Inputs
O0 ~ O7	Outputs (Inputs)
CE	Chip Enable Input
ŌĒ	Output Enable Input
V _{PP}	Program Supply Voltage
V _{DD}	Power Supply Voltage (+5V)
GND	Ground

Pin Connection (Top View)

V _{PP} C		28	D VDD
A12 🗆	2	27	A14
A7 🗖	3	26	A 13
A6 🗆	4	25	B A C
A5 🗖	5	24	D A9
A4 C	6	23	DA11
A3 E	7	22	□ O E
A2 [8	21	DA10
A1 C	9	20	DCE
A0 🗆	10	19	07
00 E	11	18	□ 06
01 🗆	12	17	D 05
02 🗆	13	16	⊒04
GND C	14	15	1 03
		_	•

Block Diagram



Operating Mode

PIN	CE (20)	OE (22)	V _{PP} (1)	V _{DD} (28)	00 ~ 07 (11 ~ 13, 15 ~ 19)	POWER
Read	L	L			Data Out	A
Output Deselect	•	Н	5V	5V	High Impedance	Active
Standby	Н	*	1		High Impedance	Standby
Program	L	Н			Data In	
Program Inhibit	am Inhibit H H 12.5V 6V		6V	High Impedance	Active	
Program Verify	•	L	1		Data Out	

^{*} H or L

Maximum Ratings

SYMBOL	ITEM	RATING	UNIT
V _{DD}	Power Supply Voltage	-0.6 ~ 7.0	
V _{PP}	Program Supply Voltage	-0.6 ~ 14.0	
V _{IN}	Input Voltage	-0.6 ~ 7.0	_ v
V _{I/O} Input/Output Voltage		-0.6 ~ V _{DD} + 0.5	
P _D	Power Dissipation	1.5	W
T _{SOLDER}	Soldering Temperature • Time	260 • 10	°C • sec
T _{STRG}	Storage Temperature	-65 ~ 125	20
T _{OPR} Operating Temperature		-40 ~ 85	_ °C

Read Mode

DC Recommended Operating Conditions

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V _{IH}	Input High Voltage	2.2	_	V _{DD} + 0.3	
V _{IL}	Input Low Voltage	-0.3	_	0.8	V
V _{DD}	Power Supply Voltage	4.75	5.00	5.25	
V _{PP}	Program Supply Voltage	V _{DD} - 0.6	V _{DD}	V _{DD} + 0.6	

DC Characteristics (Ta = -40 ~ 85°C, V_{DD} = 5V±5%)

SYMBOL	PARAMETER	TEST CONDITION		MIN.	TYP.	MAX.	UNIT
I _{LI}	Input Leakage Current	V _{IN} = 0V ~ V _{DD}	V _{IN} = 0V ~ V _{DD}		-	±10	μА
I _{DDO1}	On anotin - Course	CF 0V	f = 6.7MHz	-	_	30	
I _{DDO2}	Operating Current	CE = 0V	f = 1MHz	_	-	10	mA
I _{DDS1}	→ Standby Current —	CE = V _{IH}	•	-	-	1	
I _{DDS2}		CE = V _{DD} - 0.2V		_	-	100	μА
V _{OH}	Output High Voltage	I _{OH} = -400μA	I _{OH} = -400μA		_	_	V
V _{OL}	Output Low Voltage	I _{OL} = 2.1mA	I _{OL} = 2.1mA		_	0.4	7 '
I _{PP1}	V _{PP} Current	$V_{PP} = V_{DD} \pm 0.6V$		-	-	±10	μА
lLO	Output Leakage Current	V _{OUT} = 0.4V ~ V _I	DD D	-	_	±10	_ μΑ

AC Characteristics (Ta = -40 ~ 85°C, V_{DD} = 5V±5%, V_{PP} = V_{DD} ±0.6V)

SYMBOL	PARAMETER	TEST CONDITION	MIN.	MAX.	UNIT
t _{ACC}	Address Access Time	CE = OE = V _{IL}	-	200	
t _{CE}	CE to Output Valid	OE = V _{IL}	_	200	
toE	OE to Output Valid	CE = V _{IL}	-	70	ns
t _{DF1}	CE to Output in High-Z	OE = V _{IL}	0	60	115
t _{DF2}	OE to Output in High-Z	CE = V _{IL}	0	60	
tон	Output Data Hold Time	CE = OE = V _{IL}	0	_	

AC Test Conditions

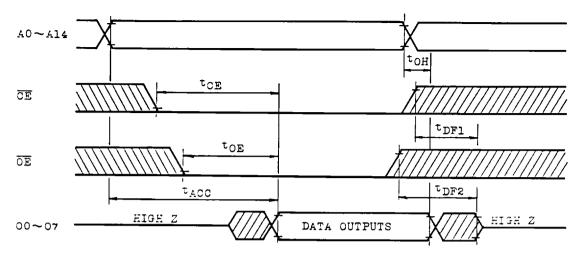
Input Pulse Levels	2.4V/0.45V
Input Pulse Rise and Fall Times	10ns max.
Input Timing Measurement Reference Levels	2.2V/0.8V
Output Timing Measurement Reference Levels	2.0V/0.8V
Output Load	1 TTL Gate and C _L = 100 pF

Capacitance* (Ta = 25°C, f = 1MHz)

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
C _{IN}	Input Capacitance	$V_{IN} = 0V$	-	4	6	n.E
C _{OUT}	Output Capacitance	V _{OUT} = 0V	-	8	12	p⊦

^{*}This parameter is periodically sampled and is not 100% tested.

Timing Waveforms (Read)



Program Mode

DC Recommended Operating Conditions

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V _{IH}	Input High Voltage	2.2	_	V _{DD} + 1.0	
V _{IL}	Input Low Voltage	-0.3	_	0.8	
V _{DD}	Power Supply Voltage	5.75	6.0	6.25]
V _{PP}	Program Supply Voltage	12.0	12.5	13.0	

DC Characteristics (Ta = 25 \pm 5°C, V_{DD} = 6V \pm 0.25V, V_{PP} = 12.5V \pm 0.5V)

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
lu	Input Leakage Current	V _{IN} = 0 ~ V _{DD}	_	-	±10	μА
V _{OH}	Output High Voltage	I _{OH} = -400μA	2.4	- 1	_	V
V _{OL}	Output Low Voltage	I _{OL} = 2.1mA	-	-	0.4	¬
I _{DD}	V _{DD} Supply Current	-		- "	40	mA
I _{PP2}	V _{PP} Supply Current	V _{PP} = 13.0V	-	-	50	
V _{ID}	A9 Auto Select Voltage	-	11.5	12.0	12.5	V

AC Programming Characteristics (Ta = 25 \pm 5°C, V_{DD} = 6V \pm 0.25V, V_{PP} = 12.5V \pm 0.5V)

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
t _{AS}	Address Setup Time	- 2		-		μs
t _{AH}	Address Hold Time	-	2	-	-	μ3
t _{CES}	CE Setup Time	-	0	-	_	ns
t _{CEH}	CE Hold Time	_	0	-	-	113
t _{OES}	OE Setup Time	-	2			
t _{DS}	Data Setup Time	-	2	-		
t _{DH}	Data Hold Time	-	2	-	_	μs
t _{VPS}	V _{PP} Setup Time	-	2	-	_	
t _{VDS}	V _{DD} Setup Time	-	2	_		
t _{PW}	Initial Program Pulse Width	CE = V _{IL} , OE = V _{IH}	0.95	1	1.05	ms
topw	Overprogram Pulse Width	Note 1	2.85	3	78.75	1113
toE	OE to Output Valid	CE = V _{IH}	-	-	150	ns
t _{DFP}	OE to Output in High-Z	CE = V _{IH}	-	-	130	113

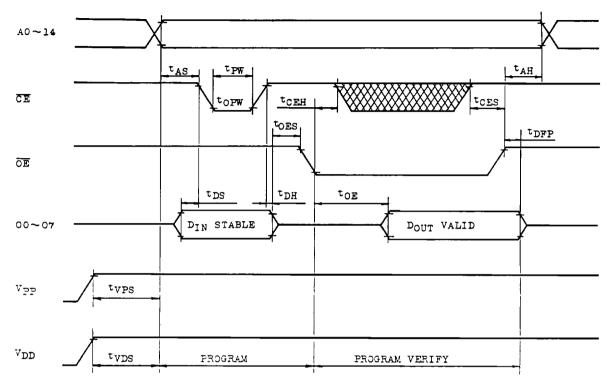
Note 1: The length of the overprogram pulse may vary as a function of the counter value X.

AC Test Conditions

Input Pulse Levels	2.4V/0.45V			
Input Pulse Rise and Fall Times	10ns max.			
Input Timing Measurement Reference Levels	2.2V/0.8V			
Output Timing Measurement Reference Levels	2.0V/0.8V			
Output Load	1 TTL Gate and C _L = 100 pF			

Timing Waveforms (Program)

$V_{DD} = 6V \pm 0.25V$, $V_{PP} = 12.5V \pm 0.5V$



Notes

- 1. V_{DD} must be applied simultaneously or before V_{PP} and cut off simultaneously or after V_{PP}
- 2. Removing the device from a programming socket and replacing the device in the socket while V_{PP} = 12.5V may cause permanent damage to the device.
- 3. The V_{PP} supply voltage is permitted to be up to 14V for programming. Voltages over 14V should not be applied to the V_{PP} terminal. When the programming voltage is applied to the V_{PP} terminal, the overshoot voltage should not exceed 14V.

Operation Information

The TC54256AP/AF's six operating modes are listed in the following table. Mode selection is achieved by applying TTL level signals to appropriate inputs.

PIN NAMES (NUMBER)			OE (22)	V _{PP} (1)	V _{DD} (28)	00 ~ 07 (11 ~ 13, 15 ~ 19)	POWER	
Read Operation (Ta = -40 ~ 85°C)	Read	L	L			Data Out	Active	
	Output Deselect	*	Н	5V	5V	High Impedance	Active	
	Standby	Н	*			High Impedance	Standby	
Program Operation (Ta = 25±5°C)	Program	L	Н			Data In		
	Program Inhibit	Н	Н	12.5V	6V	High Impedance	Active	
	Program Verify	*	L			Data Out		

Notes: $H = V_{IH}$, $L = V_{IL}$, $^* = V_{IH}$ or V_{IL}

Read Mode

The TC54256AP/AF has two control inputs. The chip enable (\overline{CE}) input controls the operating power and should be used for device selection while the output enable (\overline{OE}) input controls the output buffers. Assuming that $\overline{CE} = \overline{OE} = V_{IL}$, once the address has stabilized, output data will be valid after the address access time has elapsed.

The \overline{CE} to output valid time (t_{CE}) is equal to the address access time (t_{ACC}).

Assuming that $\overline{CE} = V_{|L}$ and that the address has been stable for at least t_{ACC} , then output data will be valid after t_{OE} from the falling edge of \overline{OE} .

Output Deselect Mode

If $\overline{CE} = V_{IH}$ or $\overline{OE} = V_{IH}$, the outputs will be in a high impedance state.

Therefore, two or more devices can be connected together on a common bus if the output of only one device is enabled. When CE is used for device selection, all deselected devices are in the low power standby mode.

Standby Mode

The TC54256AP/AF has a low power standby mode controlled by the CE signal.

By applying a MOS high level voltage (V_{DD}) to the CE input, the TC54256AP/ĀF is placed in the standby mode which reduces the operating current to 100µA and puts the outputs in a high impedance state, independent of the OE input.

Program Mode

When the TC54256AP/AF is initially received by customers, all bits of the device are in the "1" state, which is the erased state. Therefore, the object of the program operation is to introduce "0" data into the desired bit locations.

The TC54256AP/AF is in the programming mode when $V_{PP} = 12.5V$, $\overline{OE} = V_{II}$, and $\overline{OE} = V_{IH}$.

The TC54256AP/AF can be programmed at any address location at any time - either individually, sequentially, or at random.

Program Verify Mode

The verify mode is used to check that the desired data has been correctly programmed. The verify mode is activated when $\overline{OE} = V_{ii}$.

Program Inhibit Mode

When the programming voltage (+12.5V) is applied to the V_{PP} terminal, a high level \overline{CE} input inhibits the TC54256AP/AF from being programmed.

The programming of two or more TC54256AP/AFs in parallel with different data is easily accomplished. All inputs except for CE and OE may be commonly connected, then a TTL low level program pulse is applied to the CE of the desired device only while a TTL high level signal is applied to the CE of the other devices.

High Speed Programming Mode

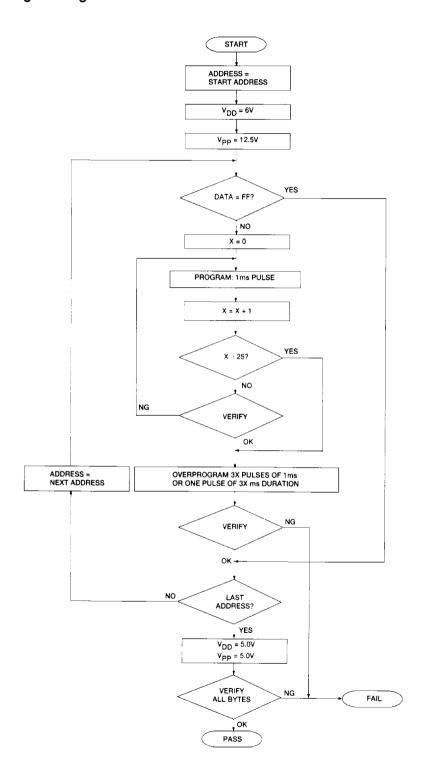
The device is set up in high speed programming mode when the programming voltage (+12.5V) is applied to the V_{PP} terminal with $V_{DD} = 6V$.

Programming is achieved by applying a single 1ms TTL low level pulse to the CE input after addresses and data are stable. Then the programmed data is verified by using the program verify mode. If the programmed data is not correct, another program pulse of 1ms is applied and then the programmed data is verified. This should be repeated until the data has programmed correctly (max. 25 times).

After correctly programming the selected address, an additional program pulse with a width of 3 times more than that needed for initial programming is applied. When programming has been completed, the data in all addresses should be verified with $V_{DD} = V_{PP} = 5V$.

High Speed Programming Mode

Flow Chart



Electric Signature Mode

The electric signature mode allows one to read out a code from the TC54256AP/AF which identifies its manufacturer and device type.

The programming equipment may read out the manufacturer code and device code from the TC54256AP/AF by using this mode before programming and automatically set the programming voltage (V_{PP}) and algorithm.

The electric signature mode is set up when 12V is applied to address line A9 and the rest of the address lines are set to $V_{\rm IL}$ during a read operation. Data output under these conditions is the manufacturer code. The device code is output when address A0 is set to $V_{\rm IH}$. These two codes possess an odd parity with the parity bit being the MSB (O7). The following table shows the electric signature of the TC54256AP/AF.

PINS	A0 (10)	07 (19)	06 (18)	05 (17)	04 (16)	03 (15)	02 (13)	01 (12)	00 (11)	HEX. DATA
Manufacturer Code	VIL	1	0	0	1	1	0	0	0	98
Device Code	V _{IH}	1	1	0	0	0	1	0	0	C4

Notes: A9 = $12V\pm0.5V$ A1 ~ A8, A10 ~ A14, \overline{OE} , \overline{OE} = V_{II}